



General Description

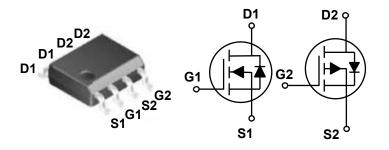
These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	Ι _D
60 V	52 mΩ	5.1 A
-60 V	100 mΩ	-3.6 A

Features

- Fast Switching
- · Green Device Available

SOP-8 Pin Configuration



Applications

- · Wireless Charging
- Boost Driver
- · Brushless Motor

Absolute Maximum Ratings T _C =25°C unless otherwise noted							
Symbol	Parameter	Rat	Rating				
V _{DS}	Drain-Source Voltage	60	-60	V			
V_{GS}	Gate-Source Voltage	±20	±20	V			
I _D	Drain Current - Continuous (T _A =25°C)	5.1	-3.6	Α			
I _{DM}	Drain Current - Pulsed (NOTE 1)	20	-14	Α			
P_{D}	Power Dissipation (T _A =25°C)	1.47		W			
T_J	Operating Junction Temperature Range	-55 to 150		°C			
T _{STG}	Storage Temperature Range	-55 to 150		°C			
Marking Code		BG052,	AP8G06S				

Thermal Characteristics						
Symbol	Parameter	Rating	Unit			
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	85	°C/W			
$R_{\theta JC}$	Thermal Resistance Junction to Case	62.5	°C/W			





N Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	60			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =48V , V_{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	IStatic Drain-Source On-Resistance	V_{GS} =10V , I_D =5A			52	mΩ
		V_{GS} =4.5V , I_D =4A			75	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.2		2.5	V
gfs	Forward Transconductance	V_{DS} =5V , I_{D} =4A		28		S

Dynamic and Switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge		-	19		
Q_{gs}	Gate-Source Charge	V_{DS} =48V , V_{GS} =4.5V , I_{D} =4A		2.6		nC
Q_{gd}	Gate-Drain Charge			4.1		
$T_{d(on)}$	Turn-On Delay Time			3		
T_r	Rise Time	V_{DD} =30V , V_{GS} =10V , R_{G} =3.3 Ω		34		nS
$T_{d(off)}$	Turn-Off Delay Time	, I _D =4A		23		110
T_f	Fall Time	1		6		
C _{iss}	Input Capacitance			1027		
C _{oss}	Output Capacitance	V_{DS} =15V , V_{GS} =0V , F=1MHz		65		pF
C _{rss}	Reverse Transfer Capacitance			45		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V , Force Current			2.5	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A			1.2	V

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed, pulse width \leq 300us, duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.



S8MBG052



60V N+P Dual Channel MOSFETs

Characteristics Curves

FIG. 1-Forward Characteristics of Body Diode

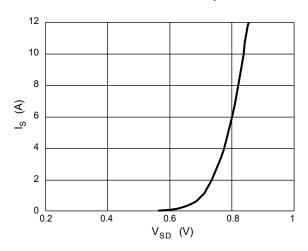


FIG. 2-Normalized $V_{GS(th)}$ vs T_J

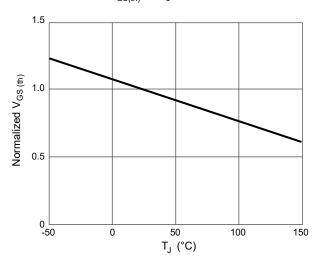


FIG. 2-Normalized $R_{DS(ON)}$ vs T_J

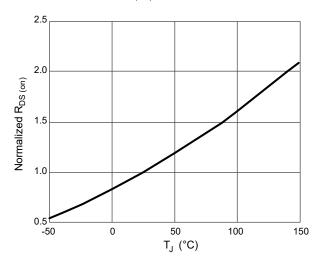


FIG. 4-R $_{DS(ON)}$ vs V_{GS}

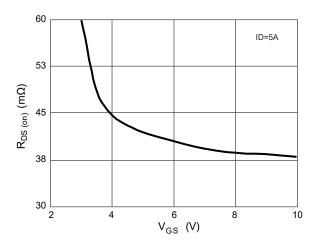


FIG. 5-Safe Operation Area

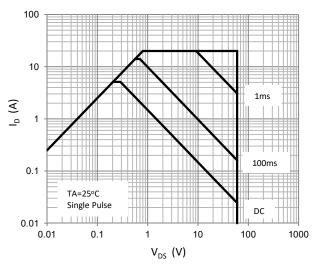
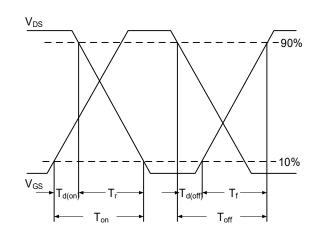


FIG. 6-Switching Time Waveform







P Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V , I _D = -250uA	-60			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} = -48V , V_{GS} = 0V			-1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = ±20V , V_{DS} = 0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	IStatic Drain-Source On-Resistance	V_{GS} = -10V , I_D = -3A			100	mΩ
		V _{GS} = -4.5V , I _D = -2A			105	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250uA$	-1.2		-2.5	V
gfs	Forward Transconductance	V_{DS} = -5V , I_{D} = -3A		8.5		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	\/ - 49\/ \/ - 45\/	-	12.1		
Q_{gs}	Gate-Source Charge	V _{DS} = -48V , V _{GS} = -4.5V , I _D = -3A	-	2.2		nC
Q_{gd}	Gate-Drain Charge	1.b 3, t	-	6.3		
$T_{d(on)}$	Turn-On Delay Time			9.2		
T _r	Rise Time	V_{DD} = -15V , V_{GS} = -10V ,		20.1		nS
$T_{d(off)}$	Turn-Off Delay Time	$R_G = 3.3\Omega$, $I_D = -1A$		46.7		110
T_f	Fall Time	7 [9.4		
C _{iss}	Input Capacitance			1137		
C _{oss}	Output Capacitance	V_{DS} = -15V , V_{GS} = 0V , F= 1MHz		76		pF
C _{rss}	Reverse Transfer Capacitance			50		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V , Force Current			-2.5	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S = -1A			-1.2	V

NOTES:

- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 5. Essentially independent of operating temperature.



S8MBG052



60V N+P Dual Channel MOSFETs

Characteristics Curves

FIG. 7-Forward Characteristics of Body Diode

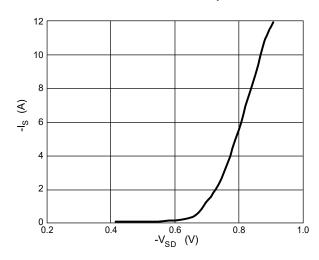


FIG. 8-Normalized $V_{GS(th)}$ vs T_J

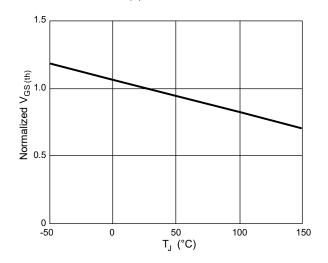


FIG. 9-Normalized $R_{DS(ON)}$ vs T_J

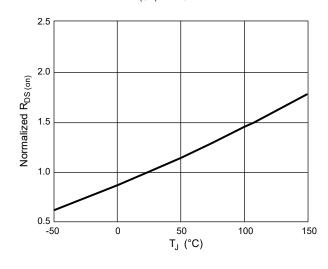


FIG. 10-Gate Charge Characteristics

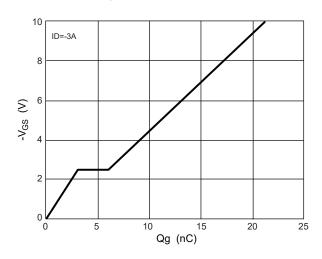


FIG. 11-Safe Operation Area

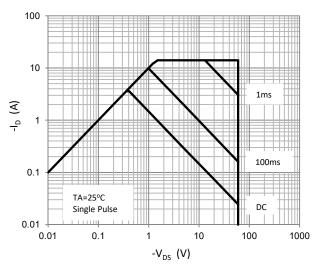
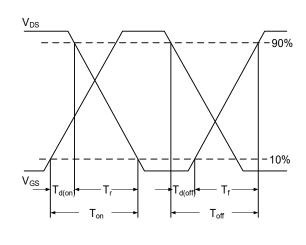


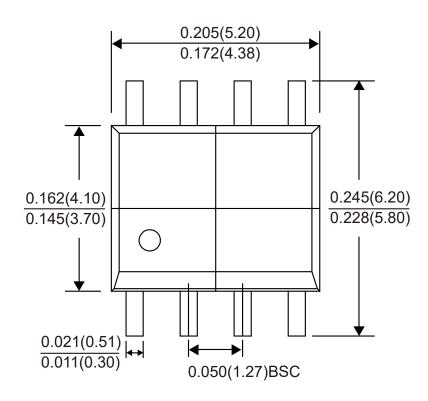
FIG. 12-Switching Time Waveform

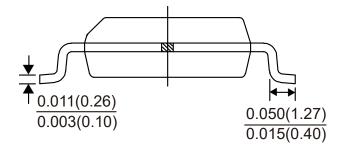


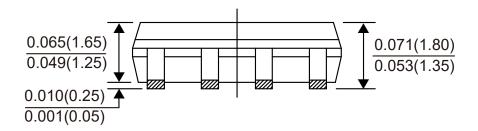




Package Outline Dimensions







SOP-8Dimensions in inches and (millimeters)





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